PCN Number:		20231016001.1				PCN Date:		October 30, 2023		
Title: Da	tasheet for	OPAS	338							
Customer Contact: Change Man			ge Mana	nagement			Dept:		Quality Services	
Proposed 1 <sup>st</sup> Ship Date: Jan.3			Jan.30,	0, 2024						
Change Typ	pe:									
Assembly Site				Design			Wafe	r Bump Site		
Assembly Process				Data Sheet			Wafer Bump Material			
	Assembly Materials			Part number change				r Bump Process		
Mechanical Specification			_	Test Site				r Fab Site		
Packing/Shipping/Labeling			ıg L	☐ Test Process		ᆜ		r Fab Materials		
				Notice that Date it		Ш	Wafei	r Fab Process		
Notification Details										
Description of Change:  Texas Instruments Incorporated is announcing an information only notification.										
The product datasheet(s) is being updated as summarized below.										
The product datasheet(s) is being updated as sufficiented below.										
TEXAS									OPA838	
INSTR	RUMENTS					SBOS	867C – A	AUGUST 20	017 - REVISED OCTOBER 2023	
				_	to Revision C (Octo				Page	
<ul> <li>Updated the numbering format for tables, figures, and cross-references throughout the document</li></ul>										
<ul> <li>Changed Device Information table to Package Information, updated columns, and added note 2</li></ul>										
• Opdated	quiescent ope	raung	current va	ilue	es in both <i>Electrical</i>	Cnaracteris	ucs ta	ibles		
The datashe	eet number	will be	e changir	าต	i					
Device Family				Change From:				Change To:		
OPA838				SBOS867B				SBOS867C		
	anc may ha									
These chang	ues may be	revie	wed at t	he	datasheet links	provided.				
-				he	datasheet links	provided.				
These chang http://www				he	datasheet links	provided.				
http://www	.ti.com/prod			he	datasheet links	provided.				
http://www Reason for	.ti.com/prod	duct/(	<u>OPA838</u>			provided.				
http://www Reason for To accurate	.ti.com/prod Change: ely reflect de	duct/(	OPA838 characte	eris	stics.					
Reason for To accurate Anticipated	Change: ely reflect de	evice	Characte	eri: <b>ur</b>	stics.	or Reliabil	lity (	positiv	ve / negative):	
Reason for To accurate Anticipated	Change: ely reflect de	evice	Characte	eri: <b>ur</b>	stics.	or Reliabil	lity (	positiv	ve / negative):	
Reason for To accurate Anticipated Electrical sp	Change: ely reflect de dimpact or recification processions and the contract of	evice Fit, perfor	characte Form, F	eri: <b>ur</b> ha	stics.	o <b>r Reliabi</b> ld above.	lity (	positiv	ve / negative):	
Reason for To accurate Anticipated Electrical sp	Change: ely reflect de dimpact or recification processions and the contract of	evice Fit, perfor	characte Form, F	eri: <b>ur</b> ha	stics. action, Quality o	o <b>r Reliabi</b> ld above.	ity (	positiv	ve / negative):	
Reason for To accurate Anticipated Electrical sp Changes to None.	Change: ely reflect de dimpact on decification product id	evice Fit, perfor	characte Form, F	eri: <b>ur</b> ha	stics. action, Quality o	o <b>r Reliabi</b> ld above.	ity (	positiv	ve / negative):	
Reason for To accurate Anticipated Electrical sp Changes to	Change: ely reflect de dimpact or decification product id	evice Fit, perfor	characte Form, F	eris ur ha	stics.  Iction, Quality of the second	o <b>r Reliabi</b> ld above.	ity (		ve / negative):  DPA838IDCKT	

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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